

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1 & 2 (Canceled)

Claim 3 (Currently Amended): A test access point structure on a printed circuit board, comprising:

a trace printed along an x-y plane in an x-, y-, z-coordinate system of a dielectric, said trace generally characterized by a trace thickness along a z axis perpendicular to an x-y plane of said dielectric; and

a test access point structure conductively connected to said trace at a test access point, said test access point structure projecting along a z axis in an x-, y-, z-coordinate system above an exposed surface of said printed circuit board to be accessible for electrical probing by an external device;

wherein said trace is further characterized by a substantially constant trace width leading up to said test access point and a narrower trace width that is narrower than said substantially constant trace width at said test access point.

Claim 4 (Canceled)

Claim 5 (Withdrawn): A test access point in accordance with claim 3, wherein said test access point comprises a solder bead.

Claim 6 (Canceled)

Claim 7 (Original): A test access point in accordance with claim 3, wherein said test access point is formed integral to said trace and characterized by an increase in thickness at said test access point.

Claim 8 (Canceled)

Claim 9 (Original): A test access point in accordance with claim 3, further comprising:
a solder mask layered over said trace, said solder mask having a hole exposing said test access point structure, wherein said test access point structure projects along said z axis of said x-, y-, z-coordinate system above an exposed surface of said solder mask on said printed circuit board to be accessible for electrical probing by said external device.

Claim 10 (Withdrawn): A test access point in accordance with claim 9, wherein said test access point comprises a solder bead/bump.

Claim 11 (Canceled)

Claim 12 (Original): A test access point in accordance with claim 9, wherein said test access point is formed integral to said trace and characterized by an increase in thickness at said test access point.

Claims 13-25 (Canceled)